



Click [here](#) for the 3D model.

Dimensions	
L	1.6mm +/-0.2mm
W	3.2mm +/-0.2mm
T	0.8mm +/-0.10mm
P	0.8mm +/-0.10mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information	
Series	Array Comm COG Flex
Style	SMD Array
Description	SMD, MLCC, Array, Flex Termination, Class II
RoHS	Yes
Termination	Flexible Termination
AEC-Q200	No
Typical Component Weight	18 mg
Notes	Last Time Buy Date (LTB): May 30th, 2024.
Chip Size	0612
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	330 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	10 VDC
Dielectric Withstanding Voltage	25 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms